

HI-BOND SL20

DESCRIPTION

SL20 is a self smoothing epoxy resin flooring system which has excellent hard wearing and durable qualities combined with ease of application and maintenance.

ADVANTAGES

SL20 is ideal where a smooth, hard wearing, dust free, chemical resistance topping is required. Ideal for use in production, food and chemical processing areas, breweries, etc.

TYPICAL TEST DATA

S.G.	1.6
Volume Solids	100%
Film Thickness	Varies
Pot Life (at 20°C)	45 minutes
Application Temperature	5°to 30°C
Foot Traffic (at 20°C)	24 Hours
Full Cure(at 20°C)	7 days

SURFACE PREPARATION AND PRIMING

Surfaces should be clean, dry and free from oil and grease etc. Ideally surfaces should be mechanically abraded by either shot blasting or grinding. Acid etching is acceptable but rinsing and drying must be very thorough after application. Prime using EP1 or EP1S. Allow to dry overnight before applying SL20

MIXING AND PREPARATION

Add the SL20 hardener "Part B" to the resin component "Part A" and mix until homogeneous using a slow speed stirrer. Pour the mixture onto the prepared surface and spread evenly using a serrated trowel to the correct thickness. Roll with a spiked roller to remove entrained air.

COLOUR RANGE

Green, Blue, Red, Grey (Other colours can be made to order)

PACKAGING

SL20 is a two pack epoxy system packed in 25 kilo units

COVERAGE RATE

The coverage rate will be affected by the profile of the substrate and the thickness of the topping. For further information, please contact our technical department

STORAGE

Store in sealed containers between 5°C and 30°C

HEALTH & SAFETY

See separate Health & Safety Data Sheet

CLEANING

HiSolve or similar should be used for cleaning tools etc.

WARRANTY DISCLAIMER

The technical data herein has been compiled for your help and guidance based upon our experience. As we have no control over the use to which our information is put, no warranty, expressed or implied is intended or given and we cannot be held responsible for coverage, performance or any damage incurred.

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